

Remarks

Claims 33-36 have been withdrawn from prosecution. Claims 37 and 38 are amended herein.

As now amended, independent Claim 37 defines a method of forming a plurality of wiring lines on conductive material on a board having a core layer to form a printed circuit board. The method requires first forming the plurality of wiring lines on a surface of the core layer, having first and second portions, the plurality of wiring lines formed on the surface of the core having side walls of a uniform thickness in height relative to the surface of the core layer; and then etching the first portion of a first of the plurality of wiring lines, such that the first portion has a planar surface completely across the first portion, joining the side walls, and is thinner in height relative to the surface of the core layer than the second portion, such that cross-talk noise between adjacent two wiring lines is reduced, wherein the first portion is parallel to at least one of the plurality of wiring lines other than the first of the plurality of wiring lines.

Claims 37 and 38 are rejected in the Office Action as anticipated by Galli et al. (U.S. 3,781,596), it being alleged that Galli discloses that 71 is etched to form a plurality of wiring lines (Fig. 10: col. 9, lines 10-11) on a surface of a core layer, and further etching 71 using mask 74 to form a different thickness first portion 12 than a second portion 13 (Fig. 1a). Reconsideration and removal of this rejection is respectfully requested in view of the present amendment to the claims and the following remarks.

In the Galli reference, a general method of etching a portion of a wiring line is disclosed and no reference is found anywhere to reduction of cross-talk noise between adjacent wiring lines.

Galli does not disclose or suggest a first portion of a first of a plurality of wiring lines in which the first portion is parallel to a part of the other wiring lines. Galli merely discloses that the entire wiring lines, other than pads 13, be made thinner. Thus, there are no portions other than pads 13 that are thicker again. Galli discloses a wiring method for a semiconductor chip and lines extending outwardly. Portions to be etched are a few millimeters in length and have a uniform height, except for the pads 13. In the present method, the portions (first portions) of the wiring lines are dozens of millimeters relatively greater than Galli, and the portions (first portion) to be etched are parallel to each other. In the present method, portions, which are not parallel to each other, become thicker again. Thus, the present method is distinct from and patentable over the Galli teachings.

In order to emphasize these distinctions, Claim 37 has been amended to provide that the method is one "wherein the first portion is parallel to at least one of the plurality of wiring lines other than the first of the plurality of wiring lines", and Claim 38 is amended to provide that the method is one "wherein the third portion is parallel to the first portion." Such is not disclosed or suggested in the Galli reference.

In view of the present amendments to the claims, Claims 37 and 38 are believed to be patentable and early allowance thereof is respectfully requested.

If there are any issues of a minor nature remaining, the Examiner is urged to contact Applicant's attorney, the undersigned, at Area Code (202) 659-2930.

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In the event that any fees are due in connection with this paper, please charge our Deposit

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Respectfully submitted,

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